



1A SURFACE MOUNT SCHOTTKY BRIDGE

FEATURES:

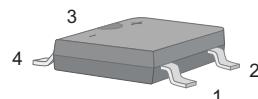
- Reverse Voltage - 40 to 200 V
- Forward Current - 1.0 A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

MECHANICAL DATA

- Case: ABS/LBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 88mg 0.0031oz



ABS/LBF Package

Maximum Ratings and Electrical characteristics

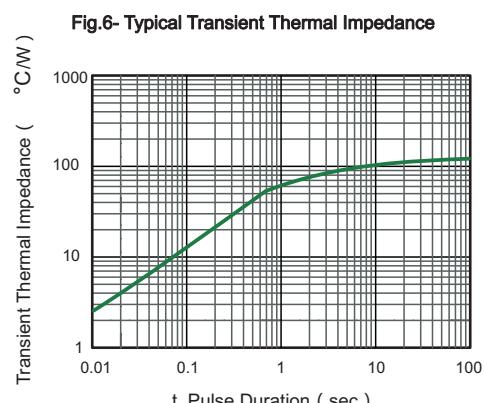
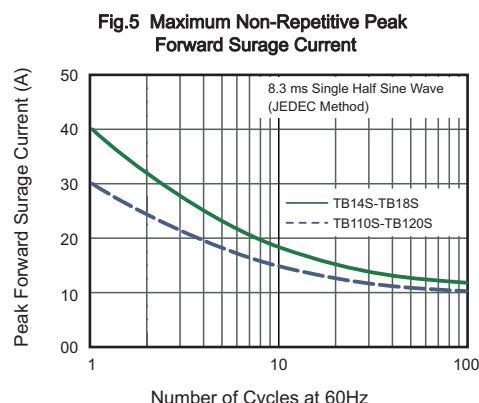
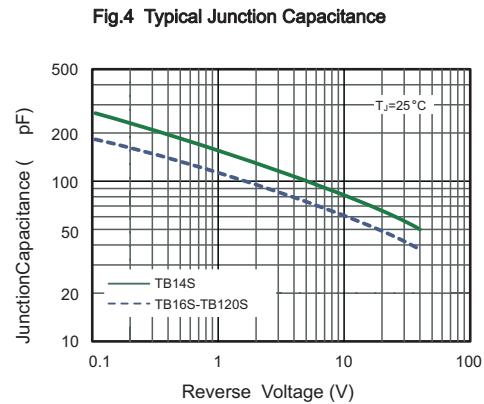
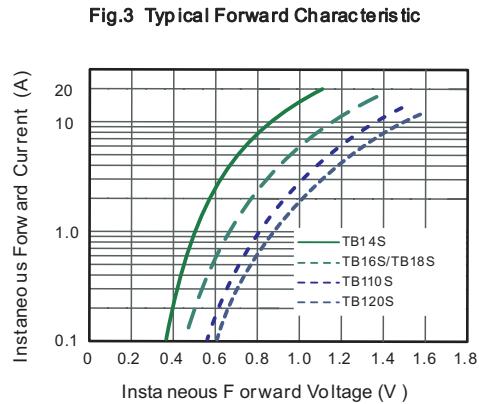
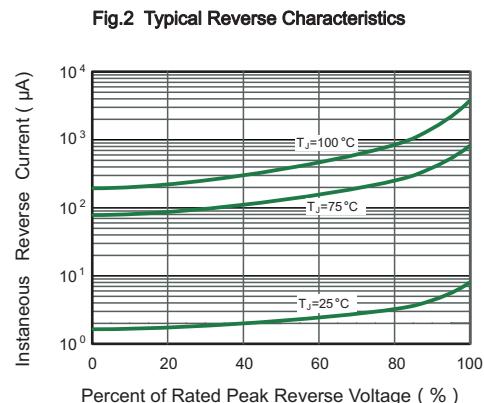
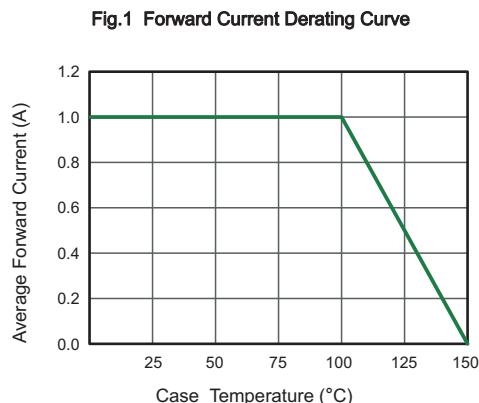
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	TB14S	TB16S	TB18S	TB110S	TB120S	Units				
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	40	60	80	100	200	V				
Maximum RMS voltage	V_{RMS}	28	42	56	70	140	V				
Maximum DC Blocking Voltage	V_{DC}	40	60	80	100	200	V				
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.0					A				
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	40		30		A					
Max Instantaneous Forward Voltage at 1 A	V_F	0.55	0.70	0.85			V				
Maximum DC Reverse Current $T_a = 25^\circ C$ at Rated DC Reverse Voltage $T_a = 100^\circ C$	I_R	0.3 10		0.2 5	0.1 2	mA					
Typical Junction Capacitance ¹⁾	C_j	110	80				pF				
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	95					°C/W				
Operating Junction Temperature Range	T_j	-55 ~ +150					°C				
Storage Temperature Range	T_{stg}	-55 ~ +150					°C				

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5" × 1.5" (3.81 × 3.81 cm) copper pad.

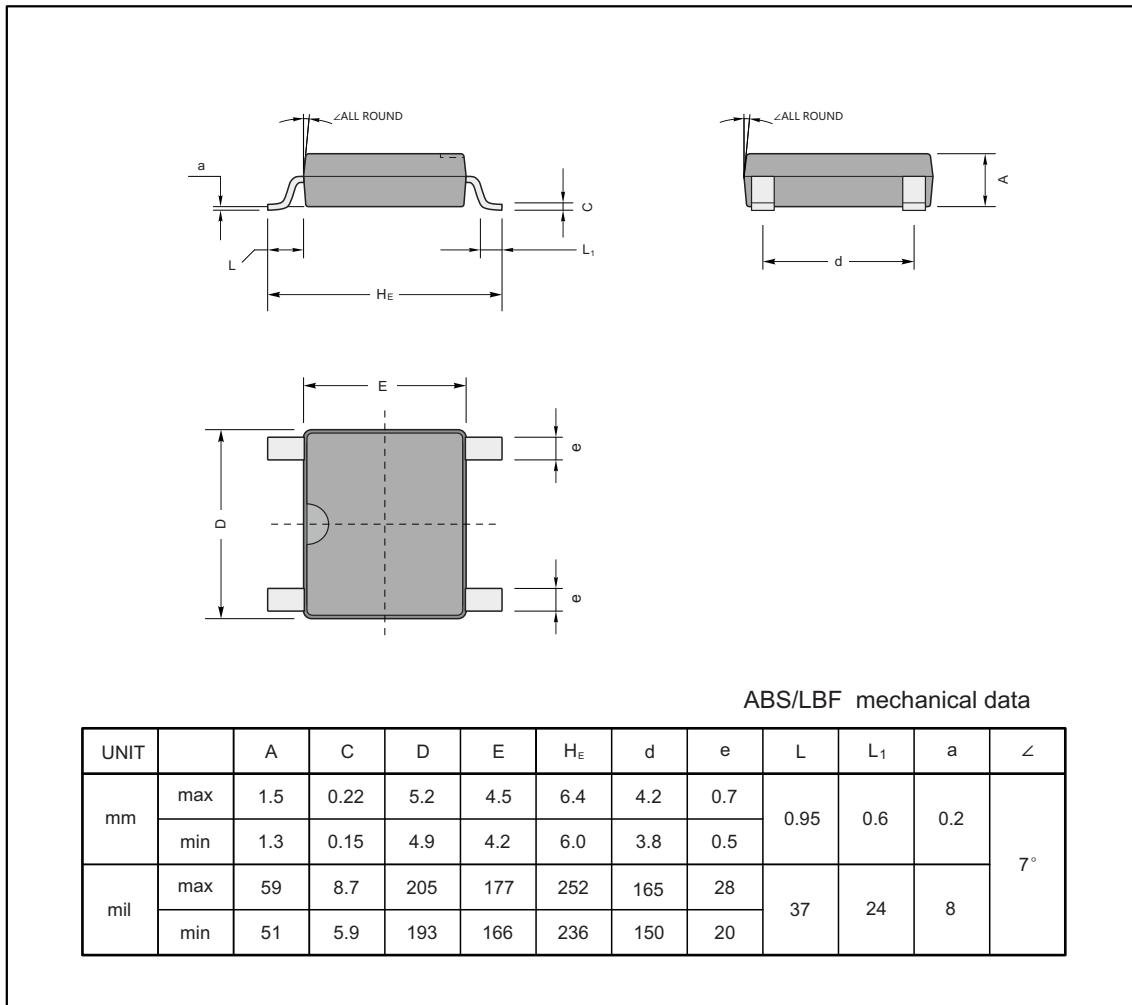




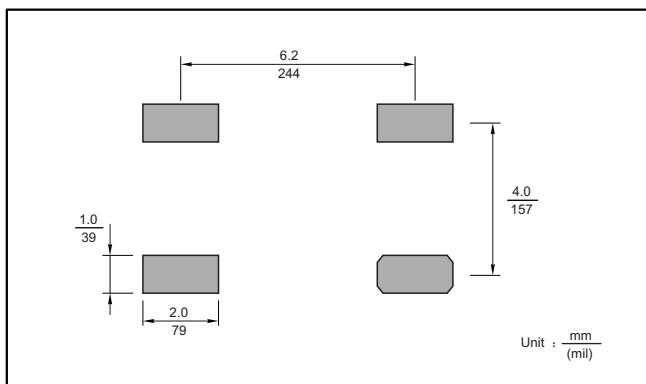
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

ABS/LBF



The recommended mounting pad size



Marking

Type number	Marking code
TB14S	TB14S
TB16S	TB16S
TB18S	TB18S
TB110S	TB110S
TB120S	TB120S